

General Description

The WST6401 is the highest performance trench P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST6401 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

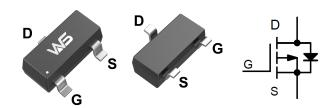
Product Summery

BVDSS	RDSON	ID
-20V	135mΩ	-2.5A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-23N Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	-20	V	
V_{GS}	Gate-Source Voltage	±12	V	
I _D @T _c =25℃	Continuous Drain Current, V _{GS} @ -4.5V ¹ -2.5			
I _D @T _c =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-1.9	А	
I _{DM}	Pulsed Drain Current ²	-10	А	
P _D @T _A =25℃	Total Power Dissipation ³	0.7	W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$	
T _J	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		178	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		80	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0 V , I_D =-250 u A	-20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25 $^{\circ}\!$		-0.016		V/℃
		V_{GS} =-4.5 V , I_D =-2 A		135	165	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =-2.5 V , I_D =-1 A		150	186	mΩ
		V _{GS} =-1.8V , I _D =-1.5A		250	355	
V _{GS(th)}	Gate Threshold Voltage	\/ =\/ = 250\	-0.5	-0.7	-1.2	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$-V_{GS}=V_{DS}$, $I_D=-250uA$		3.97		mV/℃
	Drain Source Lockage Current	V _{DS} =-16V , V _{GS} =0V , T _J =25°C V _{DS} =-16V , V _{GS} =0V , T _J =55°C			-1	uA
I _{DSS}	Drain-Source Leakage Current				-5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 8V$, V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-2A				S
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		13.1		Ω
Q_g	Total Gate Charge (-4.5V)			3.0		
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-2A		0.5		nC
Q_gd	Gate-Drain Charge			0.8		
T _{d(on)}	Turn-On Delay Time	V_{DD} =-15V , V_{GS} =-4.5V , R_{G} =3.0 Ω		10		
T _r	Rise Time			5.0		20
$T_{d(off)}$	Turn-Off Delay Time			21		ns
T _f	Fall Time			7		
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		290		
C _{oss}	Output Capacitance			60		pF
C _{rss}	Reverse Transfer Capacitance			34		

Diode Characteristics

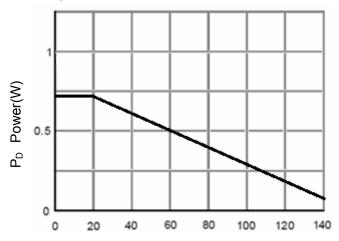
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			-2.5	Α
I _{SM}	Pulsed Source Current ^{2,4}				-10	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1.2	V

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3、Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

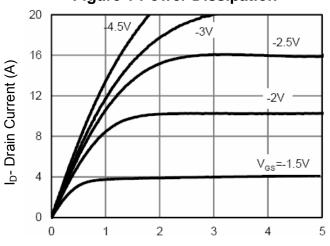






T_J-Junction Temperature(°C)

Figure 1 Power Dissipation



-Vds Drain-Source Voltage (V)

Figure 3 Output Characteristics

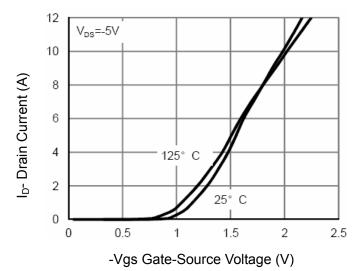
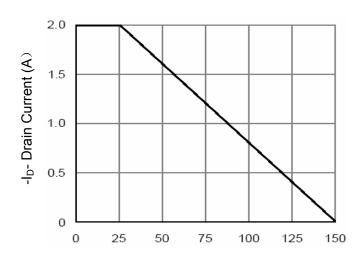


Figure 5 Transfer Characteristics



 T_J -Junction Temperature(${}^{\circ}\mathbb{C}$)

Figure 2 Drain Current

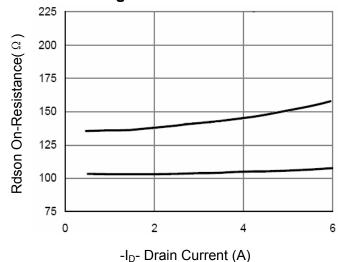
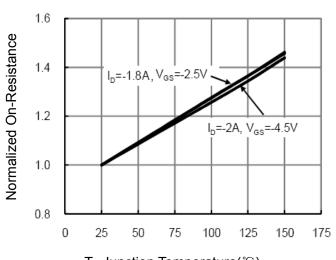


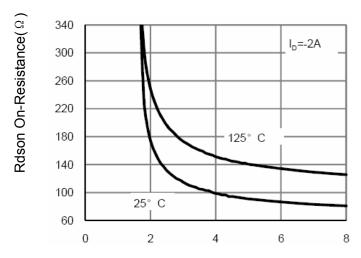
Figure 4 Drain-Source On-Resistance



T_J-Junction Temperature(°ℂ)

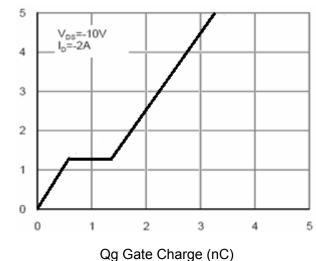
Figure 6 Drain-Source On-Resistance





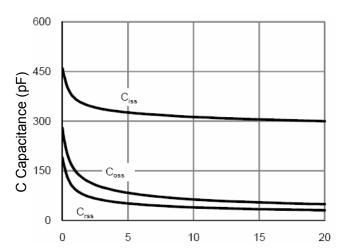
-Vgs Gate-Source Voltage (V)

Figure 7 Rdson vs Vgs



-Vgs Gate-Source Voltage (V)

Figure 9 Gate Charge



-Vds Drain-Source Voltage (V)

Figure 8 Capacitance vs Vds

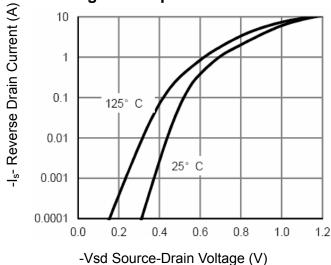


Figure 10 Source- Drain Diode Forward

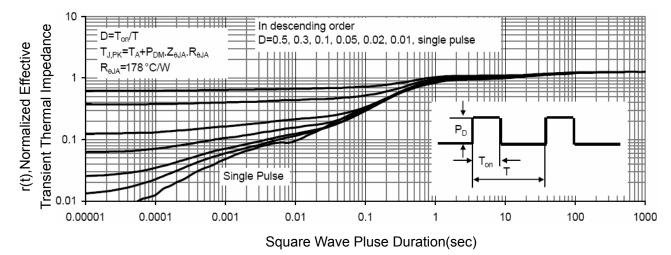


Figure 11 Normalized Maximum Transient Thermal Impedance



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